



Material Content Data Sheet



Halogen-Free

Sales Product Name	IFX1050G	Issued	03. April 2021
MA#	MA001631388		
Package	PG-DSO-8-16	Weight*	83.55 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.700	4.43	4.43	44285	44285
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8584	
	non noble metal	copper	7440-50-8	29.121	34.85	35.76	348541	357661
wire	noble metal	gold	7440-57-5	0.118	0.14	0.14	1414	1414
encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1120	
	plastics	epoxy resin	-	4.305	5.15		51531	
	inorganic material	silicondioxide	60676-86-0	42.400	50.76	56.02	507470	560121
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9741	9741
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7783	7783
glue	plastics	acrylic resin	-	0.349	0.42		4179	
	noble metal	silver	7440-22-4	1.238	1.48	1.90	14816	18995
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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